



SOT1122

plastic extremely thin small outline package; no leads; 3 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON3
Package type industry code	XSON3
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-252
Mounting method type	S (surface mount)
Issue date	9-10-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.4	-	1.45	1.5	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.55	-	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

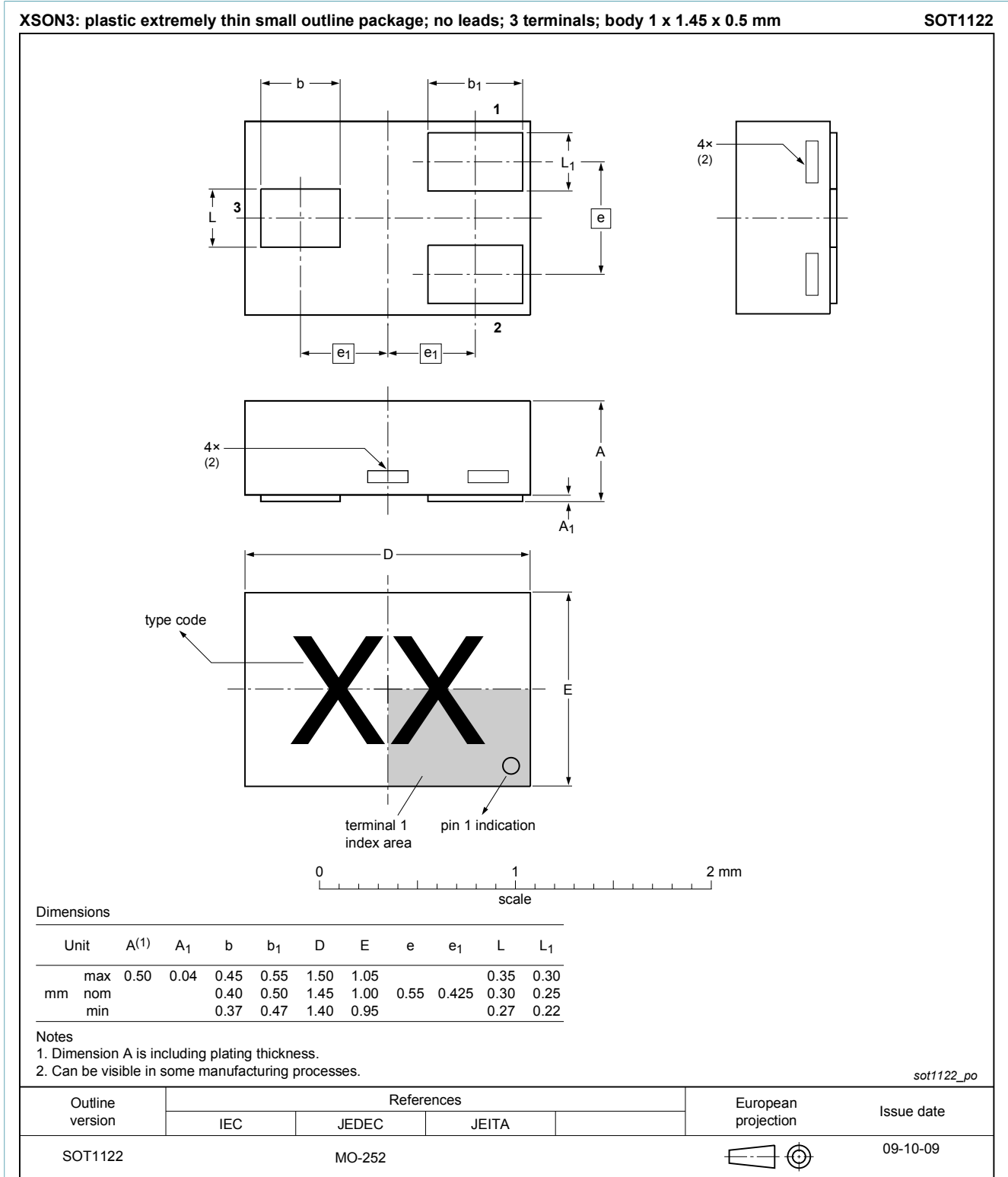


Fig. 1. Package outline XSON3 (SOT1122)

3. Soldering

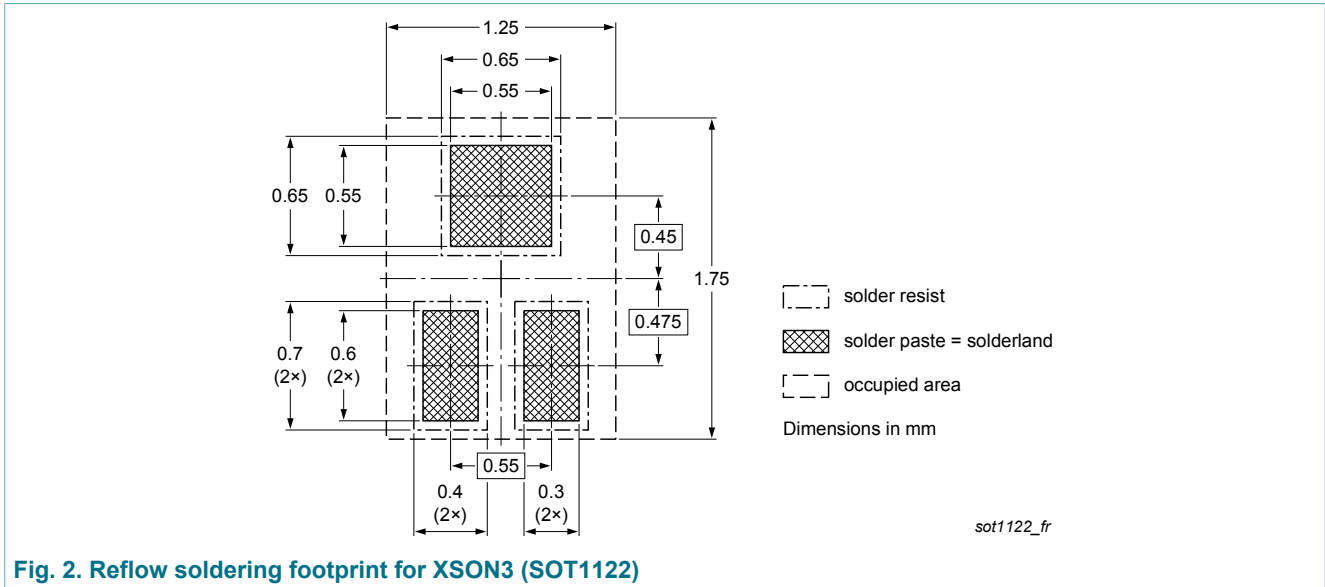


Fig. 2. Reflow soldering footprint for XSON3 (SOT1122)

4. Legal information

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